



Spatial Atomic Layer Deposition a novel very fast atmospheric pressure deposition technique

bringing new possibilities for nano-scaled and nano-designed coatings for a range of large area glass and foil based applications

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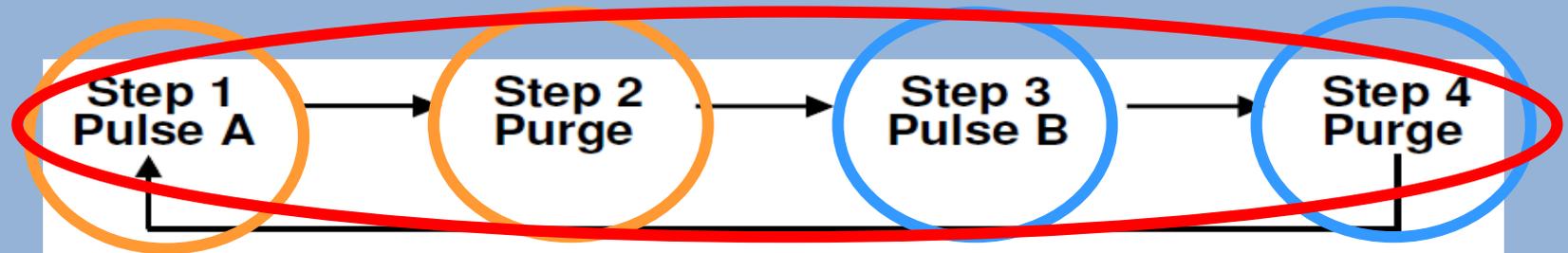
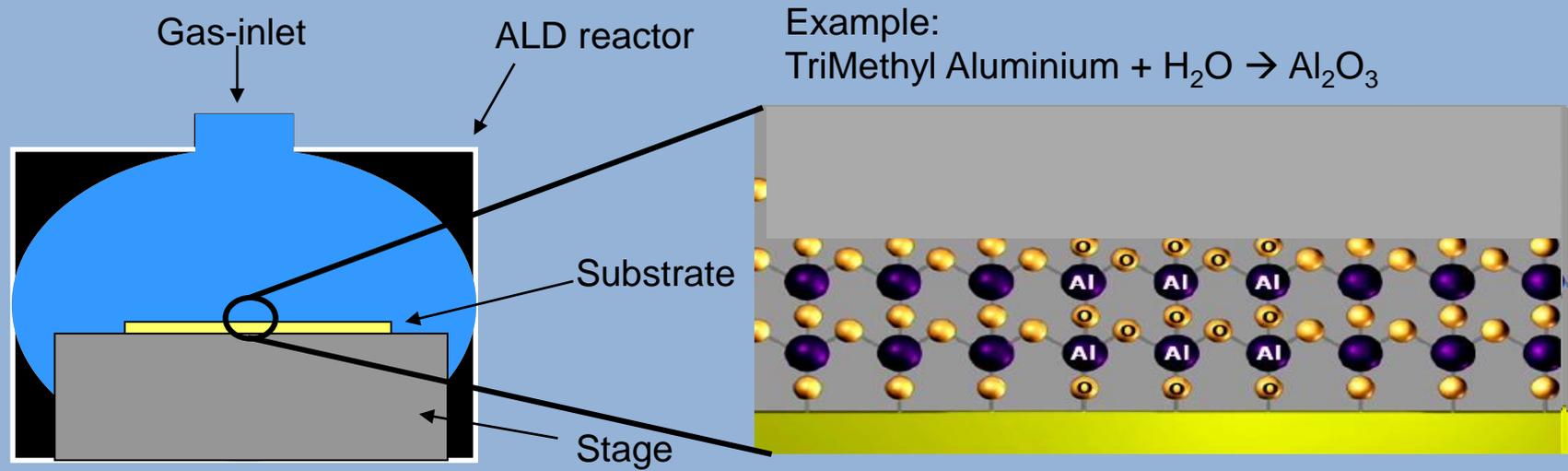
TNO



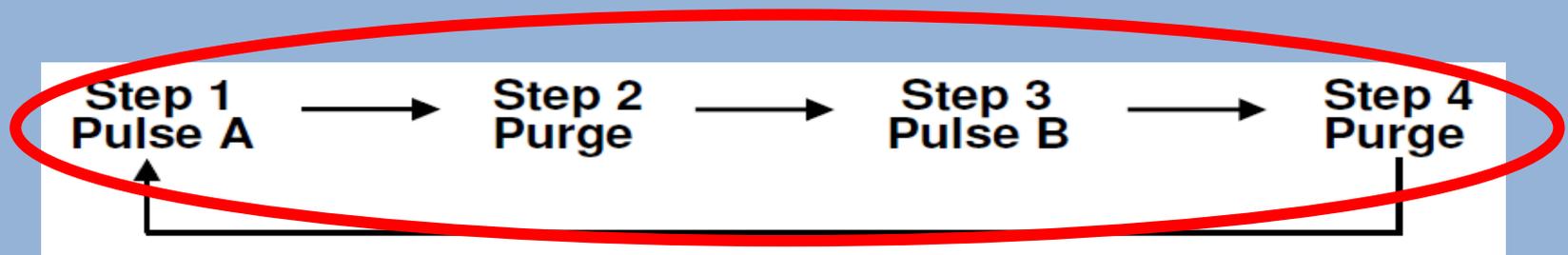
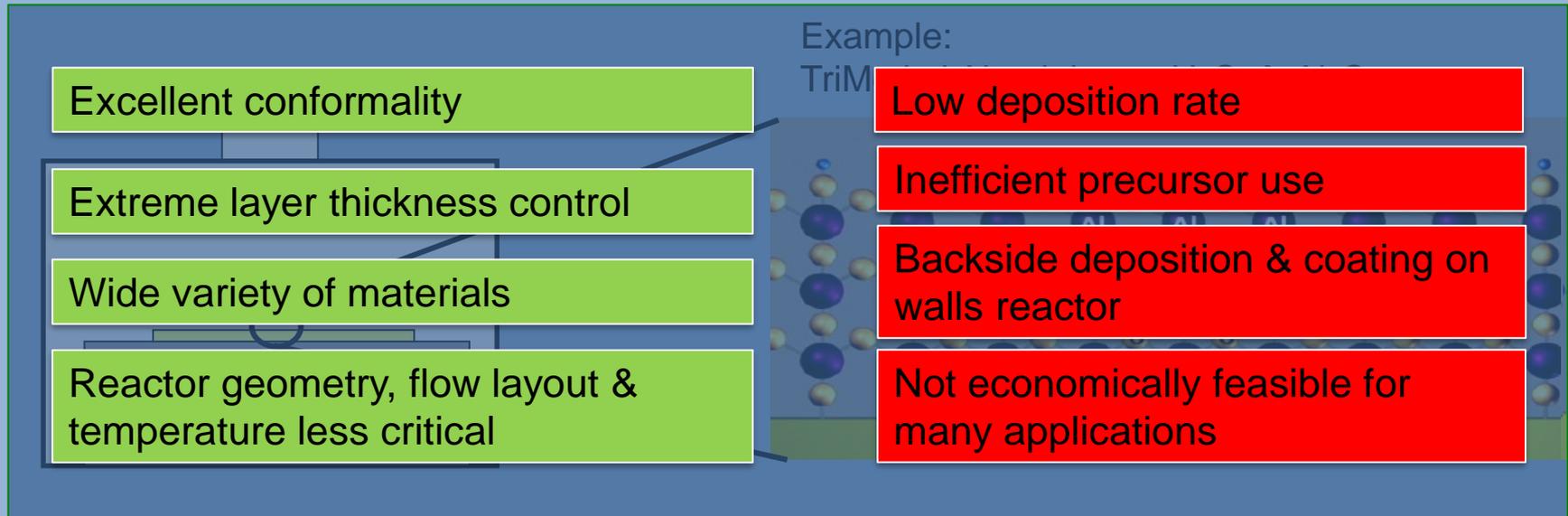
Introduction

- **Intro to spatial ALD**
- **Overview on SALD equipment**
- **Overview on Applications**
 - **Photovoltaics**
 - **Flexible electronics**
 - **Glass based products**
- **Conclusions**

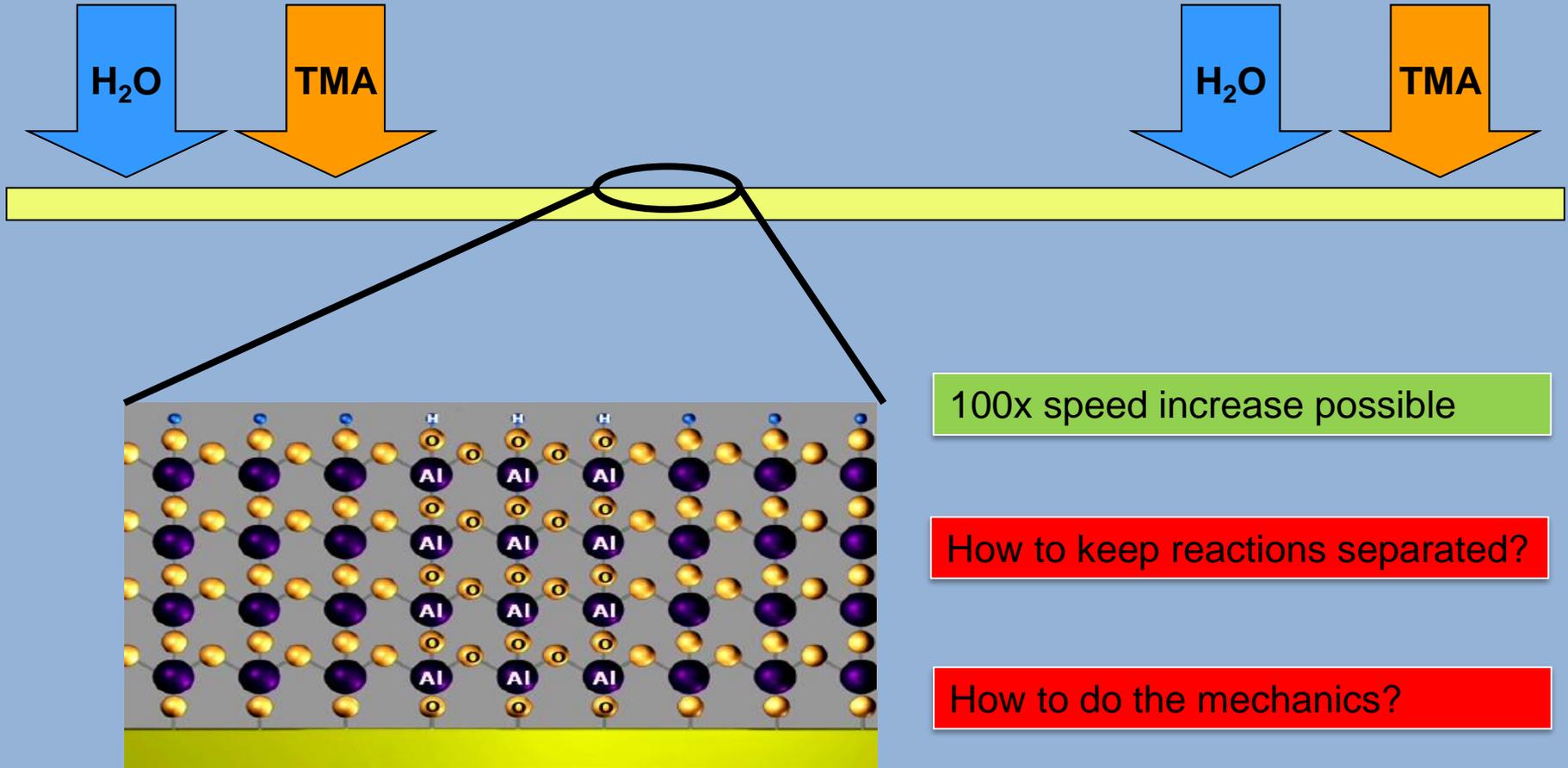
What is Atomic Layer Deposition



What is Atomic Layer Deposition

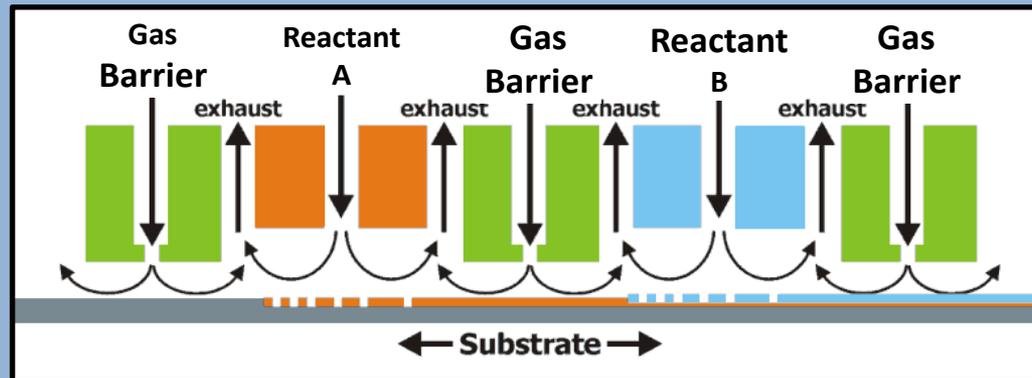


Spatial separation of half-reactions



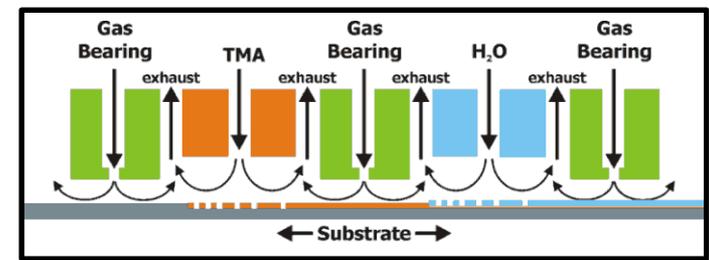
Spatial Atomic Layer Deposition

- TNO solution:
- Atmospheric pressure Spatial Atomic Layer Deposition



- Spatial separation of half reactions instead of time-separated
- Gas bearings maintain very close distance between injector and substrate → Typically 10-20 μm
- No intermixing of precursor and reactant

S-ALD Advantages



- Atmospheric pressure: no vacuum! → compatible with IJP, slot-die, etc.
- Allows roll-to-roll and large area sheet-to-sheet processing
- Deposition rates ~nm/s: Hours become minutes!
- No parasitic deposition
- High precursor yield
- Premixing of precursors possible
- Many materials deposited so far:
 - Al₂O₃, TiO₂, SiO₂, HfO₂, ZnO, Al:ZnO, In:ZnO, InZnO, InGaZnO, ZnSnO_x, Ag, Alucone (MLD) and many more

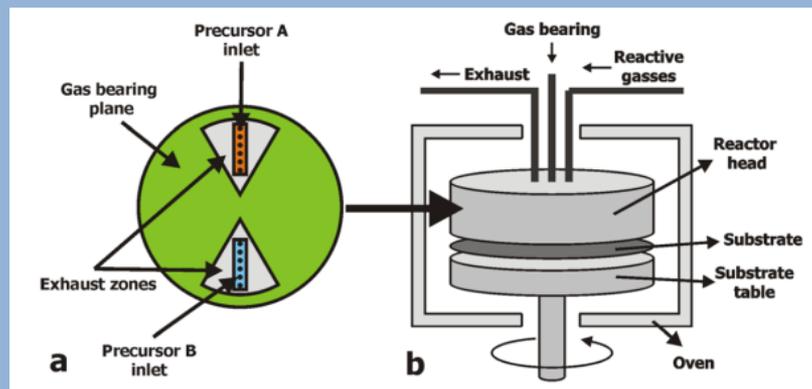
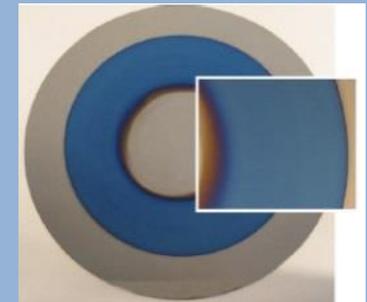
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TNO Lab reactor(s)



- Rotating reactor
- Head floating on substrate/substrate table by a gas bearing plane → Proximity 20 μm
- Total reactor placed in furnace



Poodt et al, Adv. Mat. 22(32) 2010, p. 3564–3567

SoLayTec



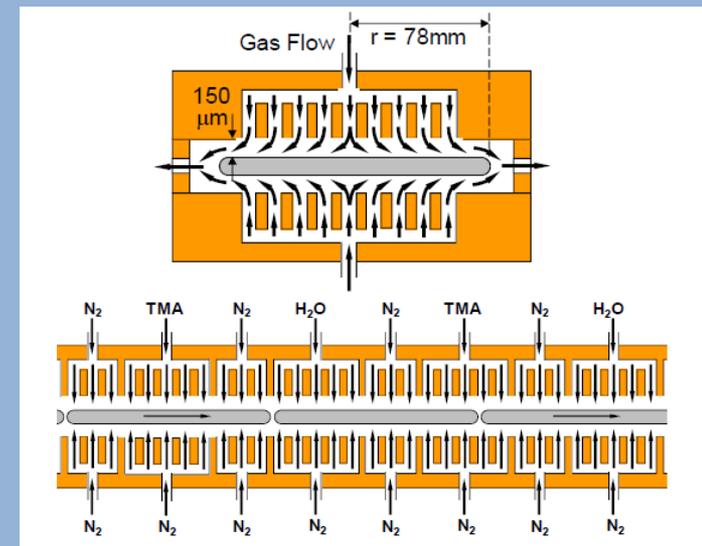
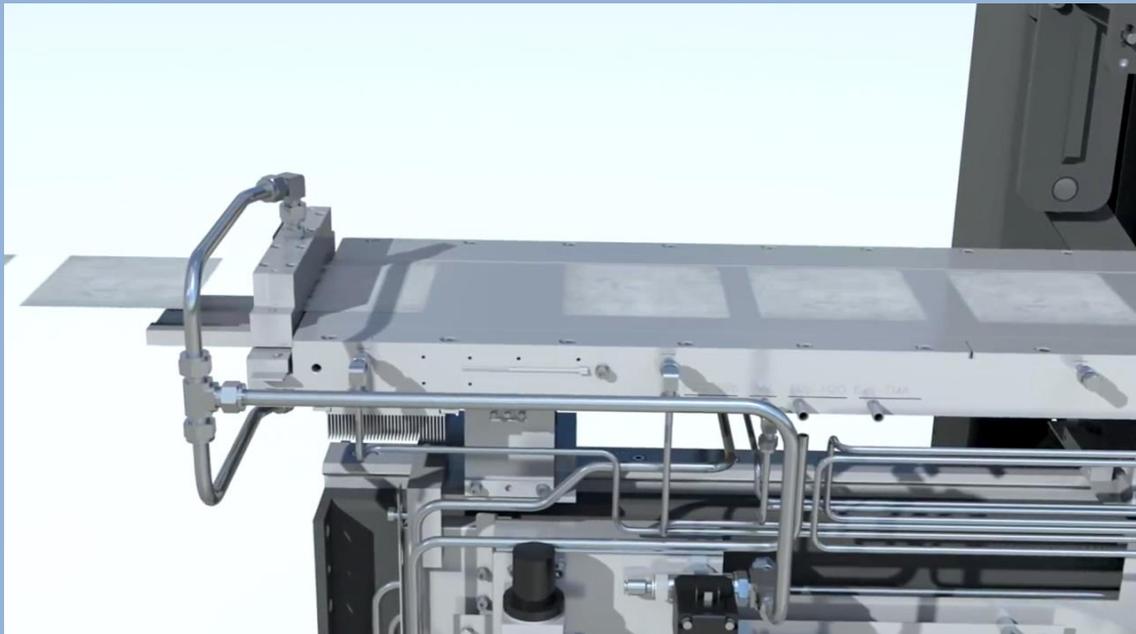
- Deposition of Al_2O_3 passivation layers on c-Si solar cells
- Up to 4800 wph; Dep. Rate 4, 6 or 8 nm/s; T_{dep} 180-225 °C

+ Input and output via:
- Manual



<https://www.youtube.com/watch?v=juXHLYfaGVU>

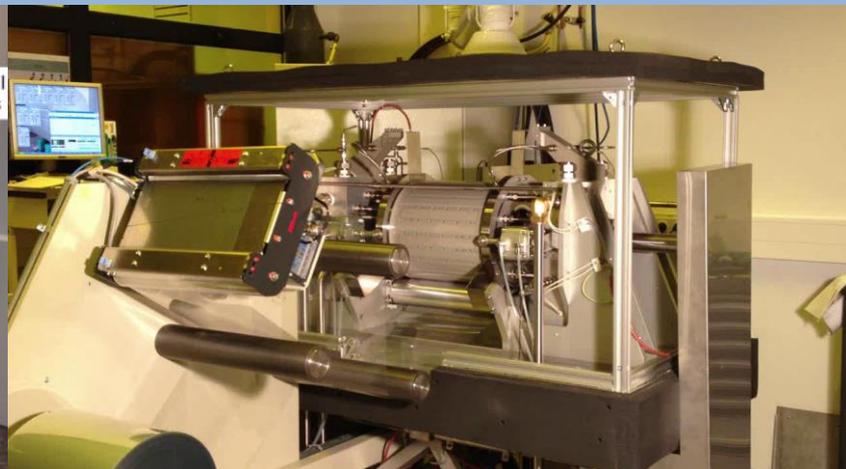
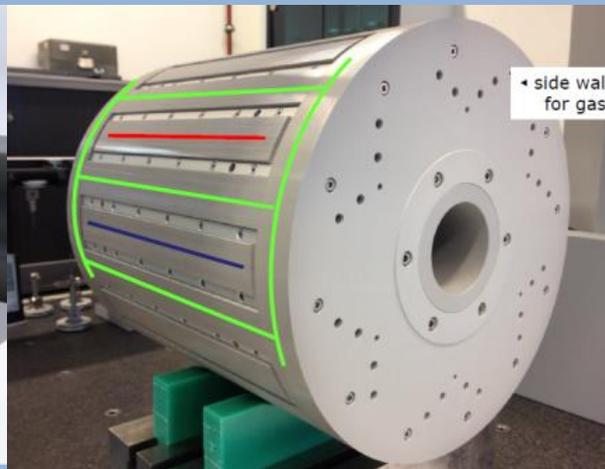
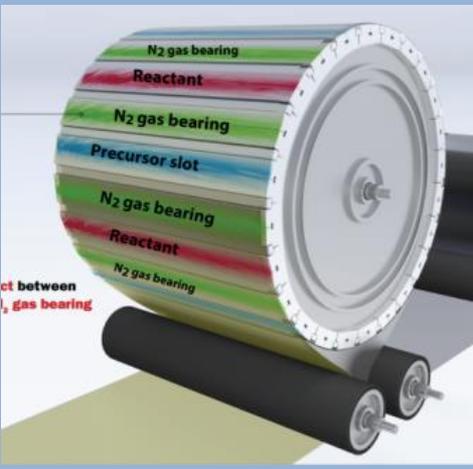
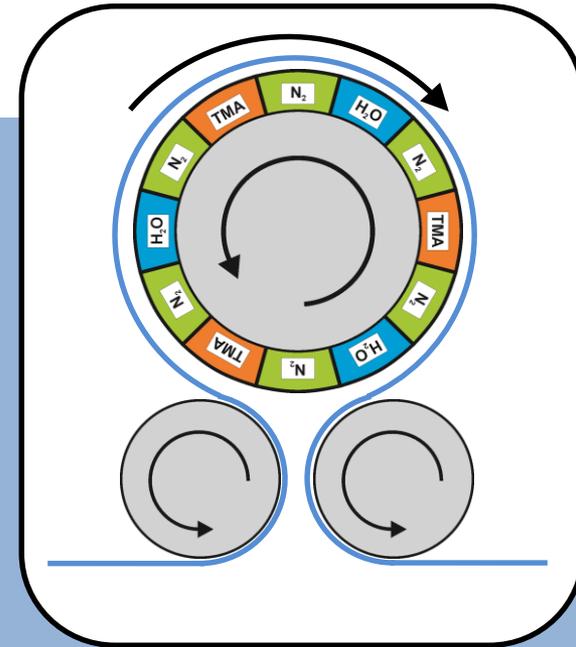
- Deposition of Al_2O_3 passivation layers on c-Si solar cells
- Up to 3600 wafers/hr; 6 nm at 1nm/meter; CoO 0.025 €/wafer
- Independent from TNO development



<https://www.youtube.com/watch?v=ywBd9K8yJX0>

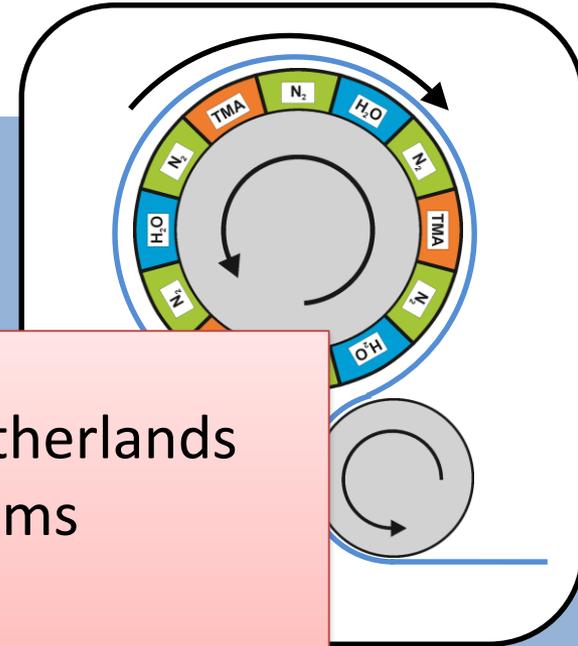
TNO R2R S-ALD

- Gas bearings prevent foil touching Drum
- Roll moves opposite foil direction
 - Foil clockwise slowly; Drum anti-clockwise fast
- Nr of cycles depends on Nr of precursor slots, speed of foil and speed of Drum



TNO R2R S-ALD

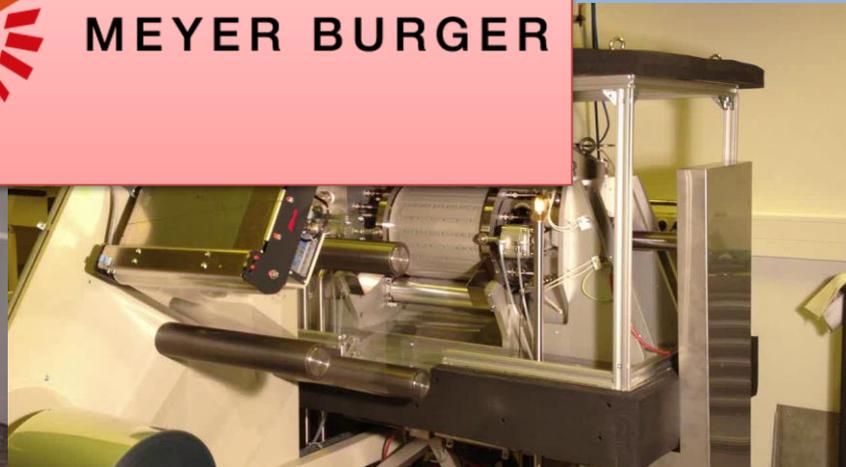
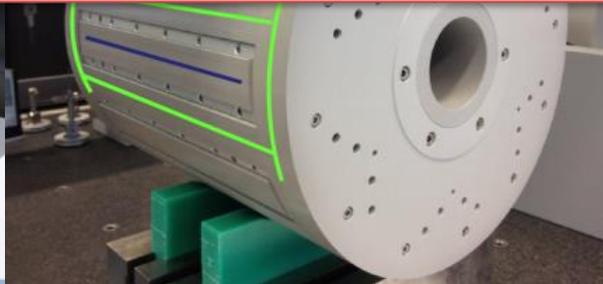
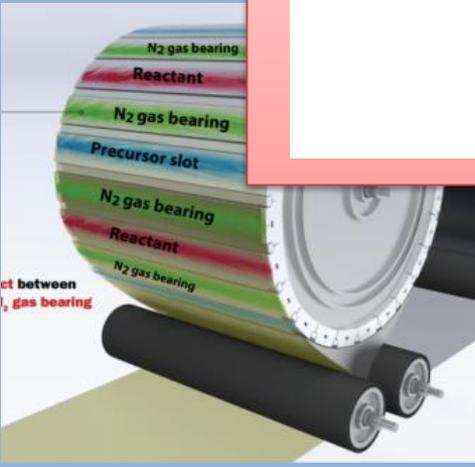
- Gas bearings prevent foil touching Drum
- Roll moves opposite foil direction
-
- No sl...



VDL-FLOW & Meyer Burger in the Netherlands sell R2R S-ALD production systems



MEYER BURGER



Up-scaling: R2R Spatial ALD

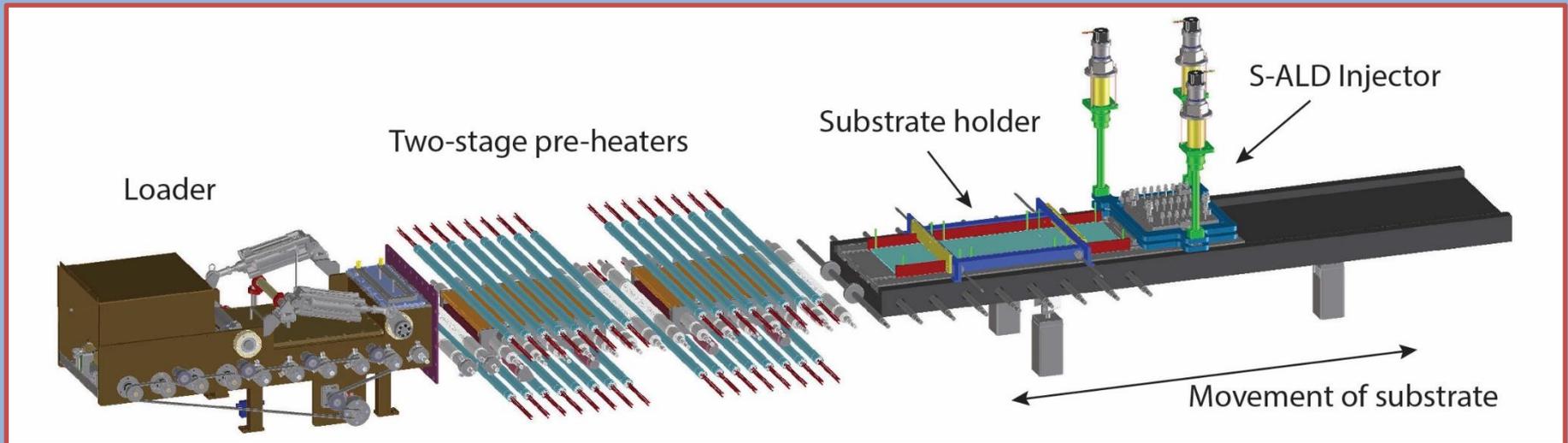


- Large-scale tool available by Meyer Burger (the Netherlands)



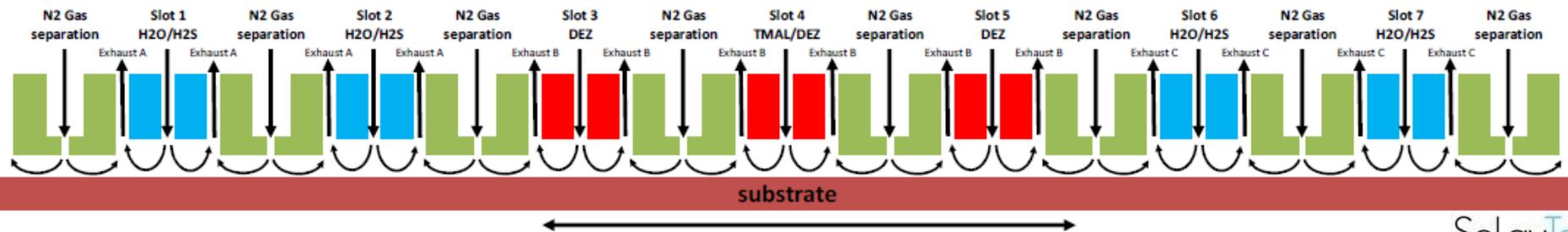
Large-area S2S Spatial ALD pilot line

- Substrate: Maximum size 325 x 400 mm (includes Gen1)
- T_{dep} up to 350°C

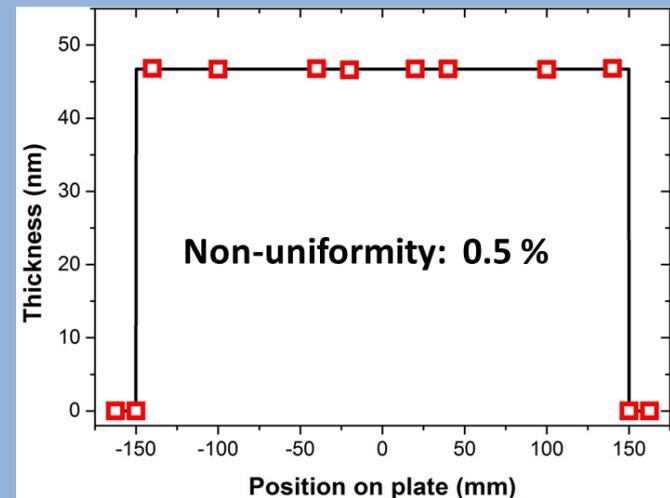
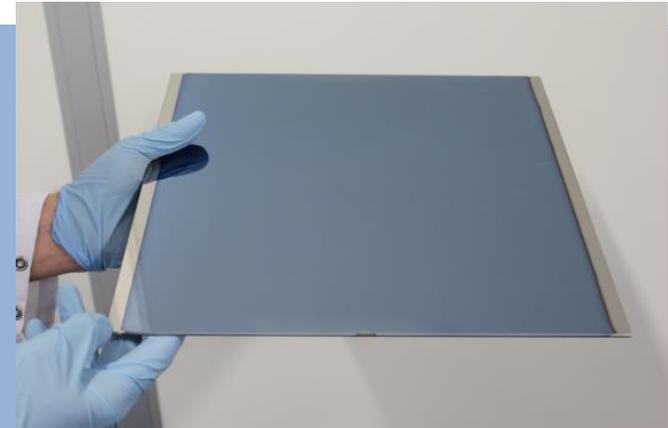


S2S SALD Pilot line

- 7 slot injector
- Precursors separated or premixed
 - H₂O & H₂S
 - DEZ & TMA
- Layers possible: ZnO, Al:ZnO, Al₂O₃, Zn(O,S), Al:Zn(O,S)



S2S SALD Pilot line

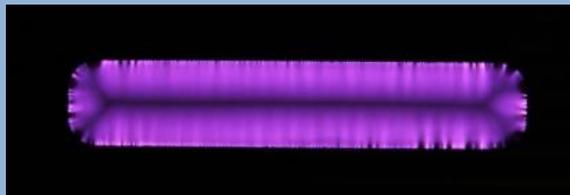


Atmospheric Plasma activated S-ALD

- Surface Dielectric barrier Discharge plasma with N_2 or O_2 plasma
- Ag, SiO_2 , ZnO, Al_2O_3 , TiO_2



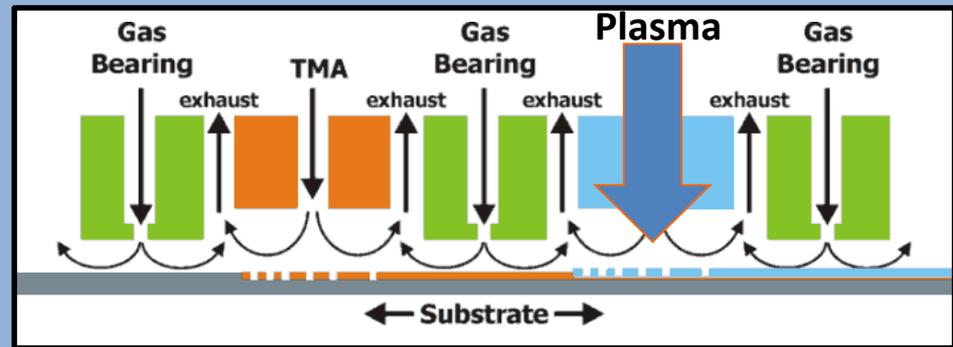
Hans Pulker Award
ICCG11



SDBD blanket



SDBD linear jet



Creygton et al, Proc. ICCG 11 Braunschweig, 2016, Developments in Plasma Enhanced Spatial ALD for High Throughput Applications

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 - Flexible electronics
 - Glass based products
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Prospects for Solar cell manufacturing

Solar cell type	Application	Thickness (nm)	ALD materials				
AlGaAs/GaAs	Multijunction Absorber	30–400	GaAs	AlGaAs	AlAs		
a-Si:H	Transparent conductive oxide	400	ZnO:B				
c-Si	Surface passivation layer	5–30	Al ₂ O ₃				
CIGS	Buffer layer	10–70	ZnSe	(Zn,Mg)O	Zn(O,S)	In ₂ S ₃	GaS
	Diffusion barrier layer	100–300	Al ₂ O ₃				
	Encapsulation layer	10–55	Al ₂ O ₃				
CdTe	Window layer/n-type layer	~100	Zn(O,S)				
Organic	Encapsulation layer	15–200	Al ₂ O ₃	Al ₂ O ₃ / HfO ₂			
	Electron selective layer	1–35	Al ₂ O ₃	ZnO	TiO ₂		
	Transparent conductive oxide	150	ZnO:Al				
Dye-sensitized	Barrier layer	0.1–25	Al ₂ O ₃	TiO ₂	HfO ₂	ZrO ₂	
	Photoanode	5–90	TiO ₂	ZnO:Al	SnO ₂	ZnO	TiO ₂ :Ta
	Blocking layer	7–20	SnO ₂	TiO ₂			
	Compact layer			HfO ₂			
	Transparent conductive oxide	7	In ₂ O ₃ :Sn				
	Sensitizer	5	In ₂ S ₃				
Heterojunction nanostructured	Absorber		Cu _x S				

Prospects for Solar cell manufacturing

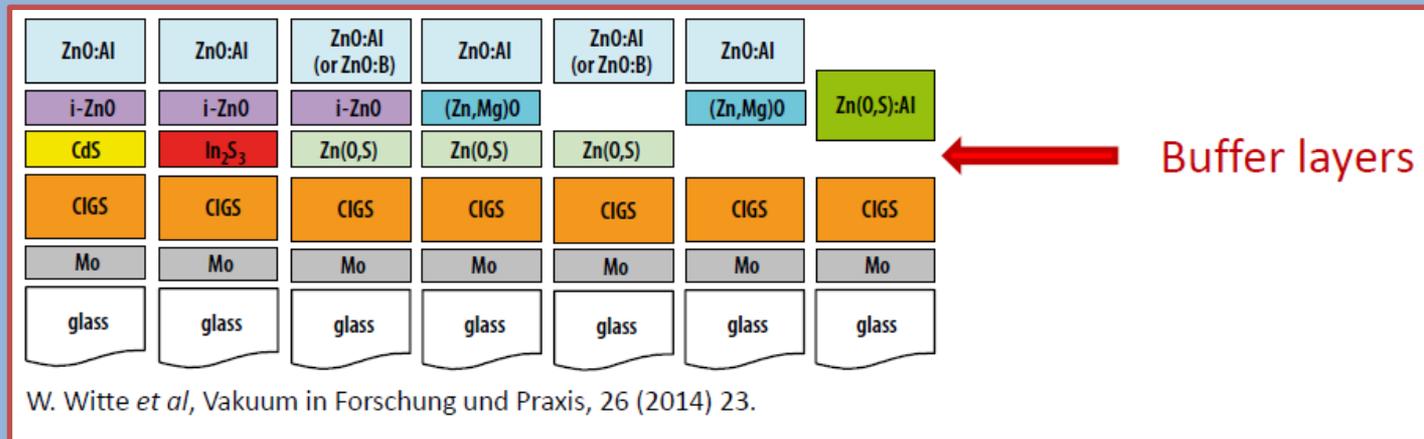
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Heterojunction nanostructured	Absorber		Cu _x S				

Production equipment by:
Solaytec
Levitech

van Delft et al, Semicond. Sci. Technol. 27 (2012) 074002

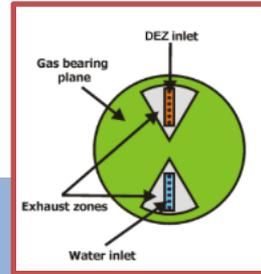
Zn(O,S) buffer layers in CIGS solar cells

- CdS buffers deposited by Chemical Bath Deposition (CBD)
 - Cd unwanted compound & CBD of CdS is strongly polluting
- Several groups studied alternatives using ALD



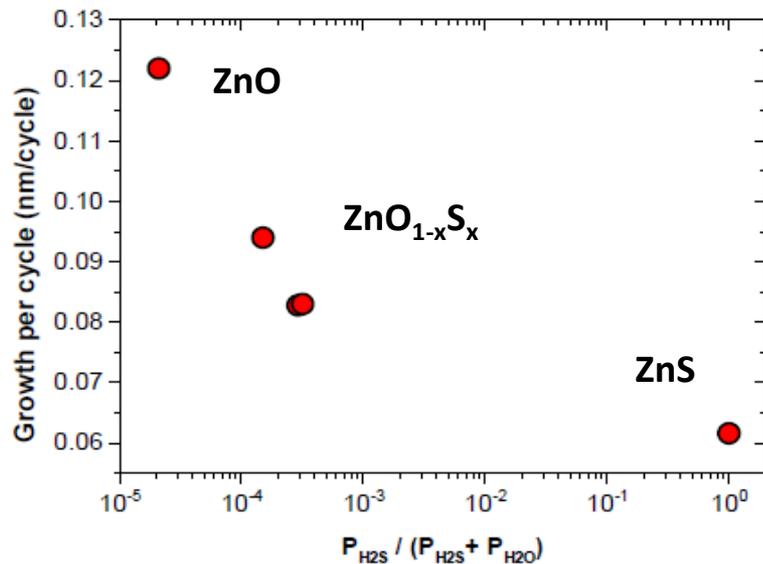
- Zn(O,S) is promising candidate
 - Increased efficiency (~+0.5%) & Comparable cost (~USD 0,02/Wp)

Zn(O,S) in labscale S-ALD reactor

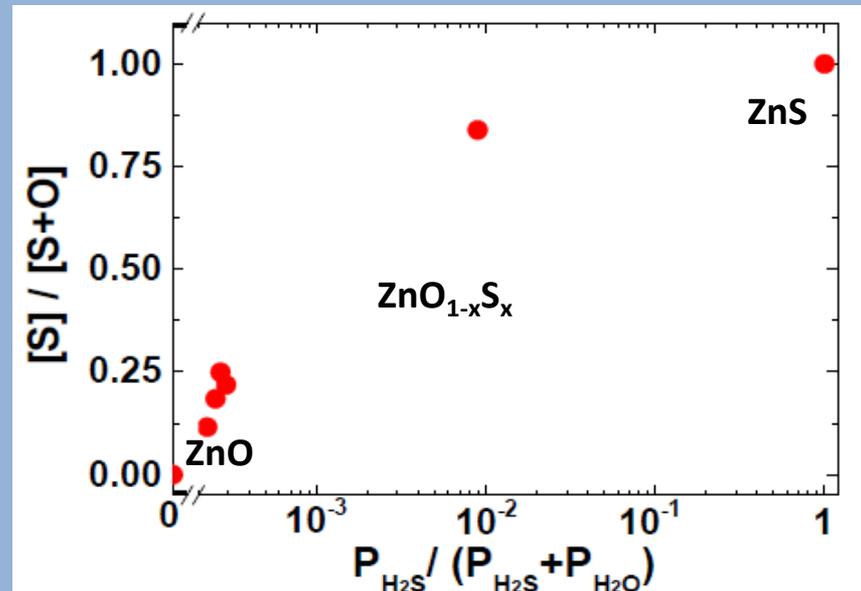


- Precursor DEZ + premix of H₂O/H₂S
- Film composition can be continuously controlled

Growth per Cycle vs H₂O/H₂S ratio



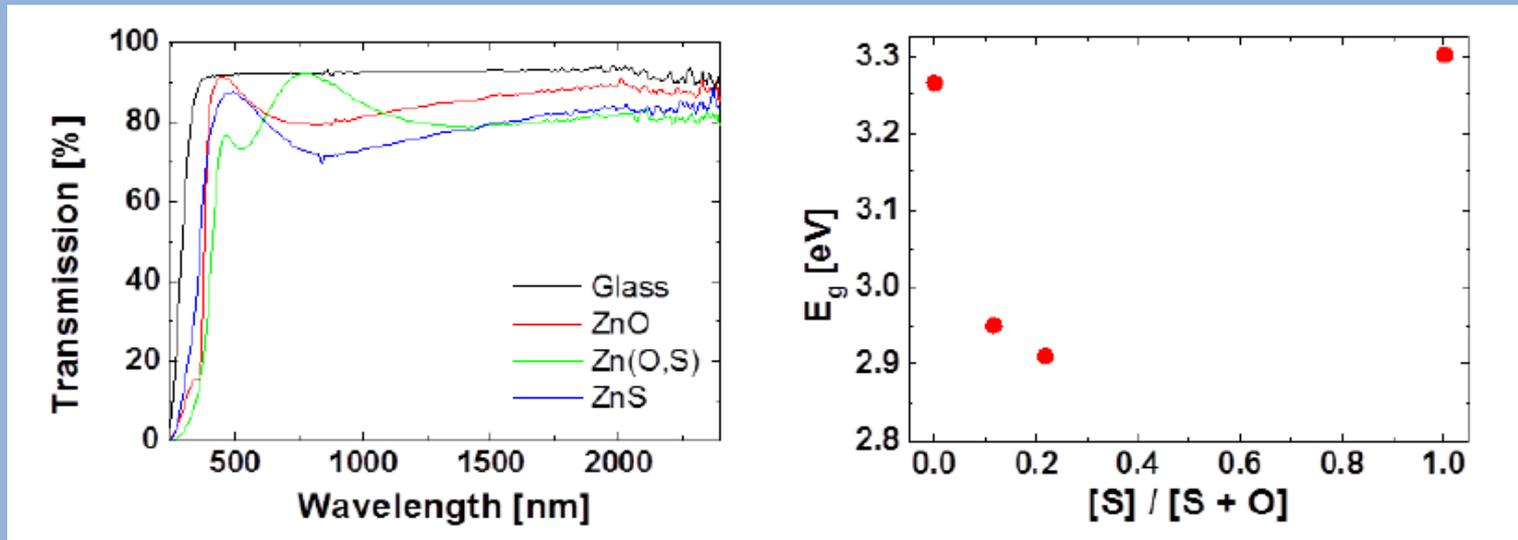
Film composition



Zn(O,S) buffer layers

Results: Transparency

- Plotted below are $\text{ZnO}_{1-x}\text{S}_x$ with $x=0$ (ZnO), $x=1$ (ZnS) and $x=0.22$
- Characteristic “bowing” of the band gap observed, according to literature



Flexible electronics

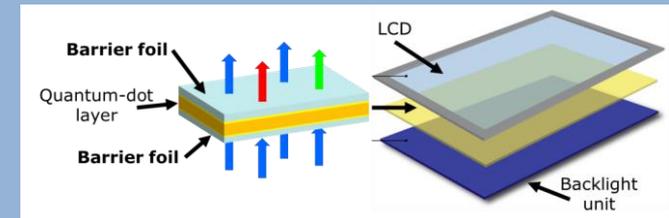
Application	ALD materials
Moisture barriers & Encapsulation	Al ₂ O ₃ HfO ₂ TiO ₂
Transparent Oxide Semiconductors Thin film transistors	GIZO, ZnO
TCO's	AZO Graphene [#]
Buffer layers	ZnO
Light management Anti-reflection	TiO ₂ , SiO ₂ , ZrO ₂

(# in development)

R2R Spatial ALD for barrier foils

■ Many applications require encapsulation

- Organic PV, CIGS, quantum-dot, Perovskites,



■ Glass-based solutions are expensive, heavy and not flexible

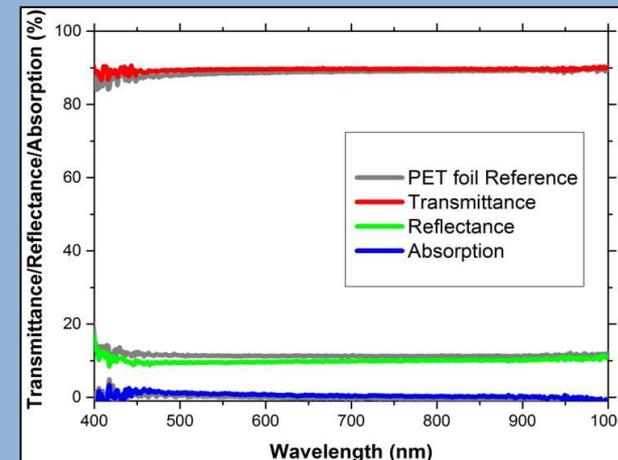
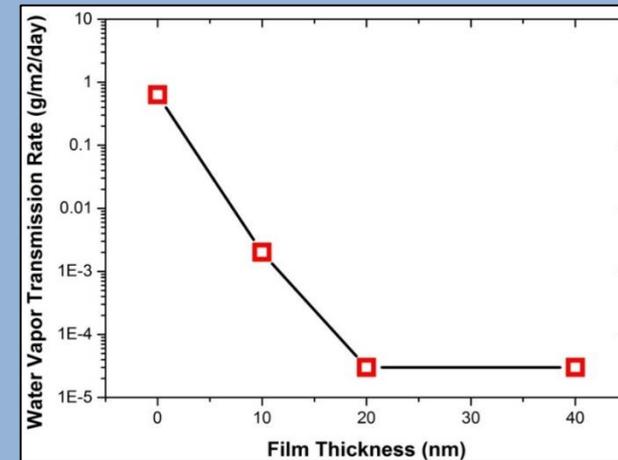
■ Barrier requirements:

- WVTR lower than 10^{-4} g/m²/day
- Highly transparent
- For PV: 20+ years lifetime
- High-throughput, low-cost



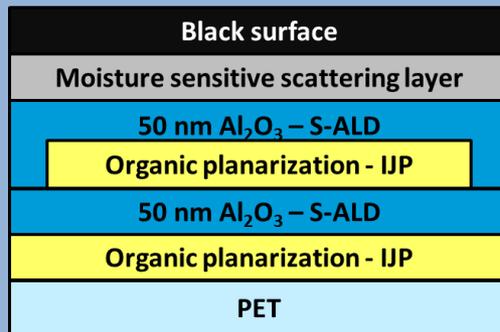
R2R Spatial ALD for barrier foils

- Example: Al_2O_3 on PET foil
- No planarization, no pre-treatment, no cleaning
- WVTR measured by optical Calcium test
- Overall WVTR for 20 nm Al_2O_3 :
 - 2×10^{-5} g/m²/day at 20 °C/50 %RH
 - 4×10^{-4} g/m²/day at 60 °C/90 %RH
- Excellent transparency



Spatial ALD of oxide semiconductors

- Sheet-to-sheet Spatial ALD for *thin-film encapsulation*
- Example: PET - Organic planarization – 50 nm Al₂O₃ – Organic – 50 nm Al₂O₃; 30 cm x 30 cm.
 - Samples were not made in cleanroom: particles unavoidable



t = 0 hrs



t = 1100 hrs at 60°C/90% RH

- No visible defects after more than 1100 hrs at 60 °C / 90 % RH
- 1100 hrs at 60 °C / 90 % RH is ~ 2.5 years at ambient conditions

InGaZnO for flexible low power consumption displays

IGZO vs a-Si:H

- 20-50 times higher electron mobility
- twice the resolution
- 80-90% power saving

It's time !



Apple

2013

Commercial rigid displays
using IGZO transistors



Dell



Apple



Asus

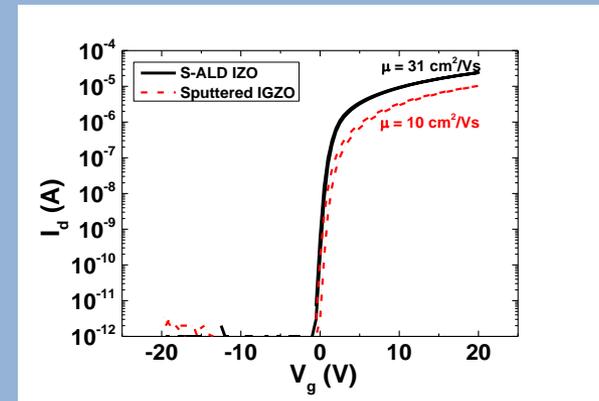
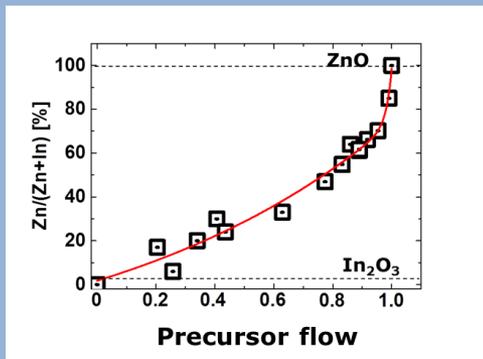
2004

First flexible transparent
transistor based on IGZO



Spatial ALD of oxide semiconductors

- Sheet-to-sheet Spatial ALD for high mobility oxide semiconductors
- Example: InZnO (IZO) oxide semiconductor → higher mobilities than IGZO
 - With our proprietary Spatial ALD process: full control of composition



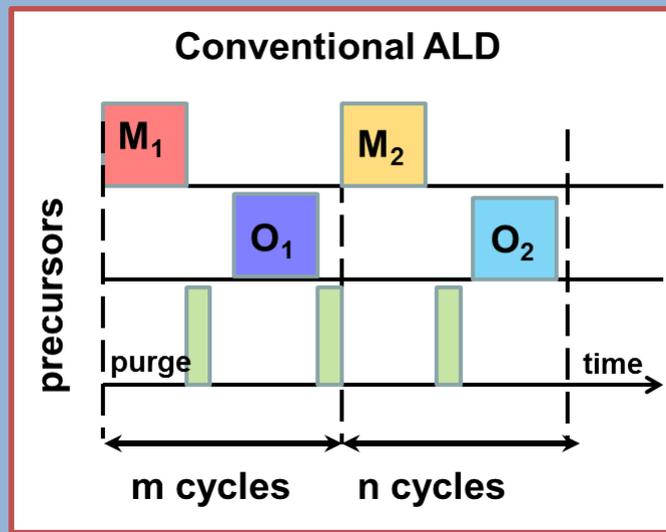
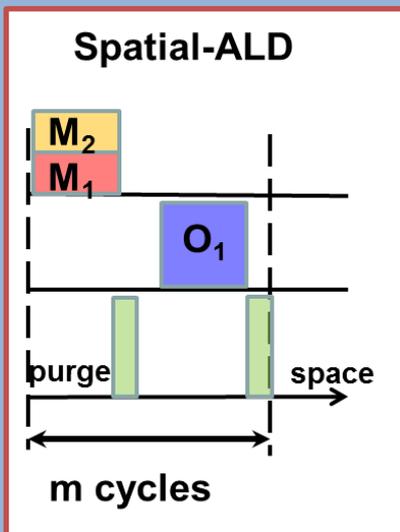
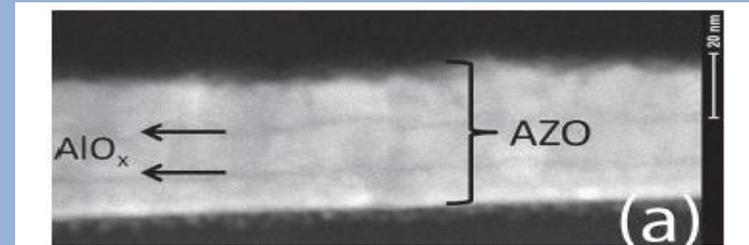
- Spatial ALD IZO Integrated ESL TFTs on 150 mm substrates
 - 15 nm SALD IZO compared to baseline 15 nm sputtered state-of-the-art IGZO
 - Mobility >30 cm²/Vs (10 cm²/Vs for IGZO), Threshold / Onset ~ 0V. Down to 5 nm channels
 - Excellent bias stress stability

Possibilities for Display, Architectural & Automotive glass

Application	ALD materials
Moisture barriers & Encapsulation	Al ₂ O ₃ HfO ₂ TiO ₂
Transparent Oxide Semiconductors Thin film transistors	GIZO, ZnO
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ALD of Al:ZnO

- Premix possible with S-ALD

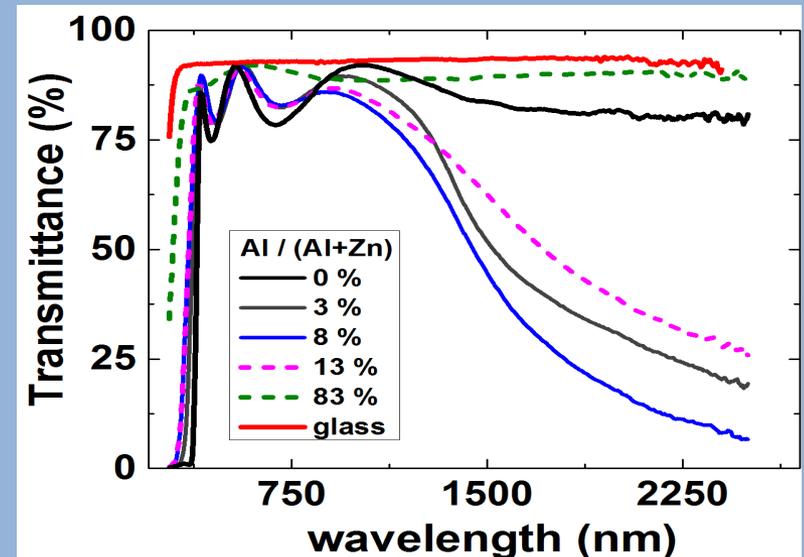
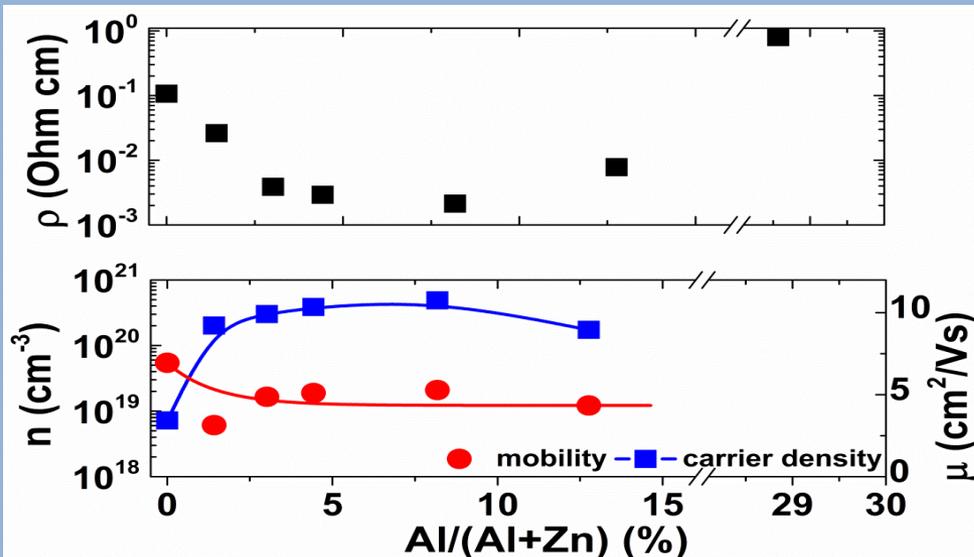


TEM cross section of Al:ZnO by conventional ALD

Y. Wu et al Journal of Applied Physics 114, 024308 (2013)

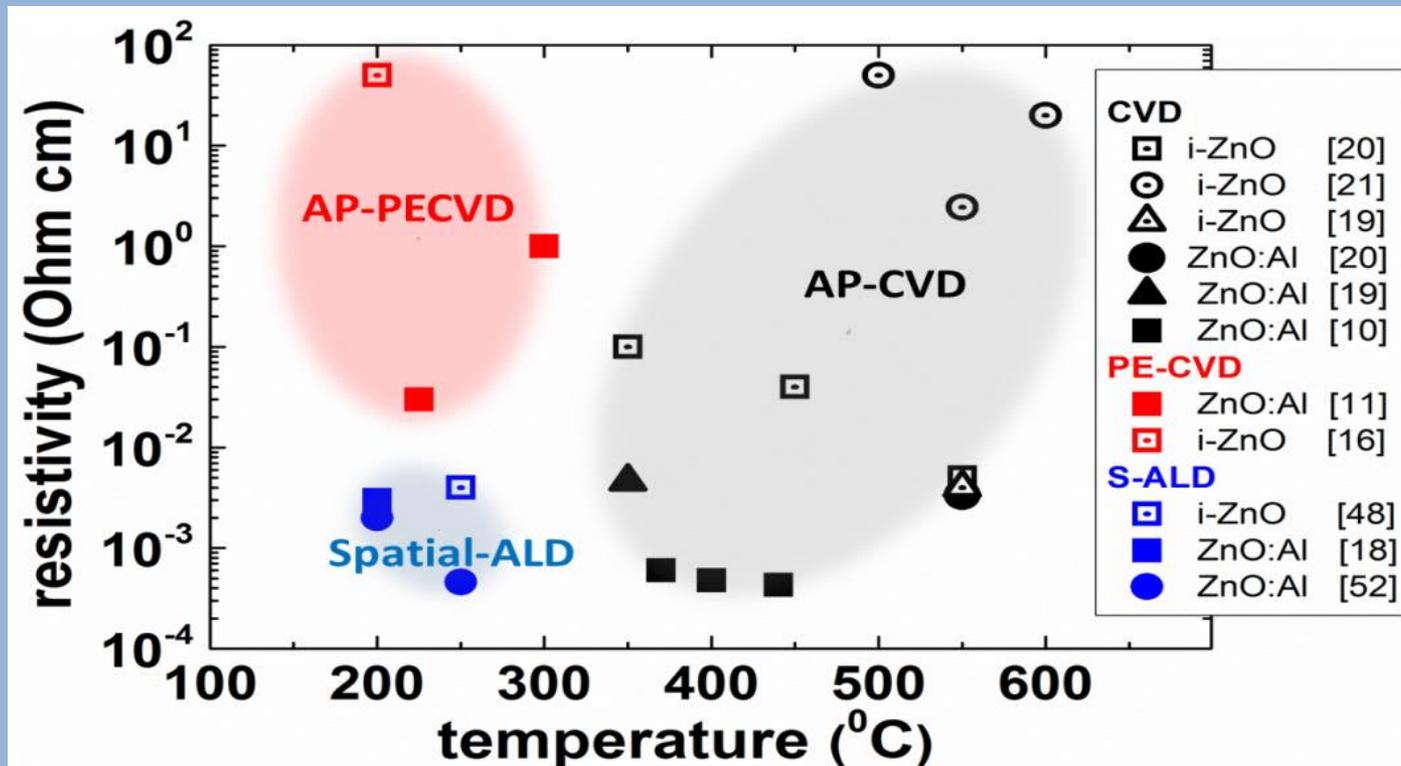
Spatial atomic layer deposition of Al:ZnO

- Precursors DMZ, TMA and H₂O



A. Illiberi et al ACS Applied Materials and Interfaces 5, 13124 (2014)

Spatial atomic layer deposition of Al:ZnO

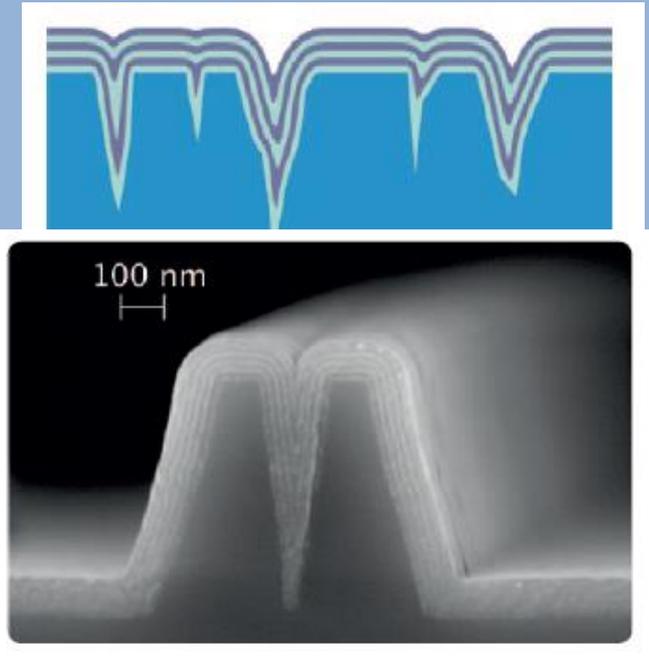
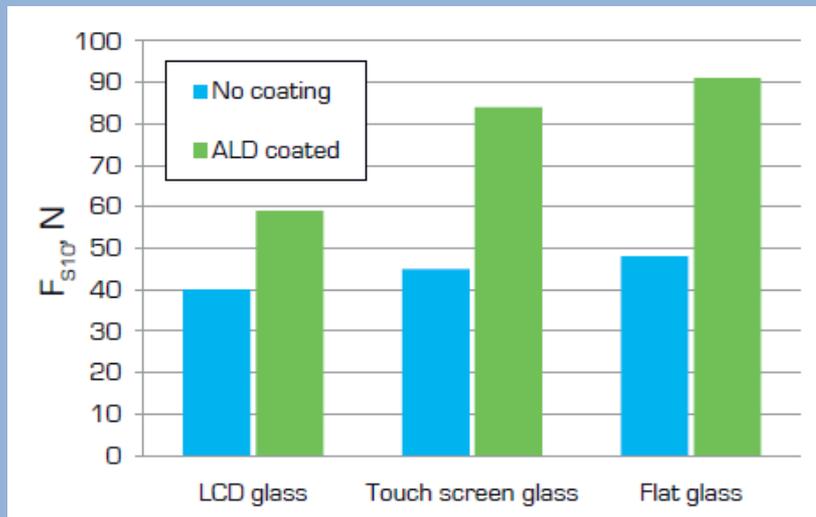


A. Illiberi et al. *Solar Energy Materials and Solar Cells* 95, 1955 (2011)

Strengthened Glass



- Beneq multilayer ALD for better glass crack resistance



Source: Beneq Strengthened Glass Brochure

Anti-reflection coatings

Optical coatings

- SiO_2 , TiO_2 , Al_2O_3 and other oxides have frequently been deposited by ALD
- Li et al deposited amorphous $\text{TiO}_2/\text{Al}_2\text{O}_3$ bilayer on BK7 @ 120°C using TiCl_4 , TMA and H_2O

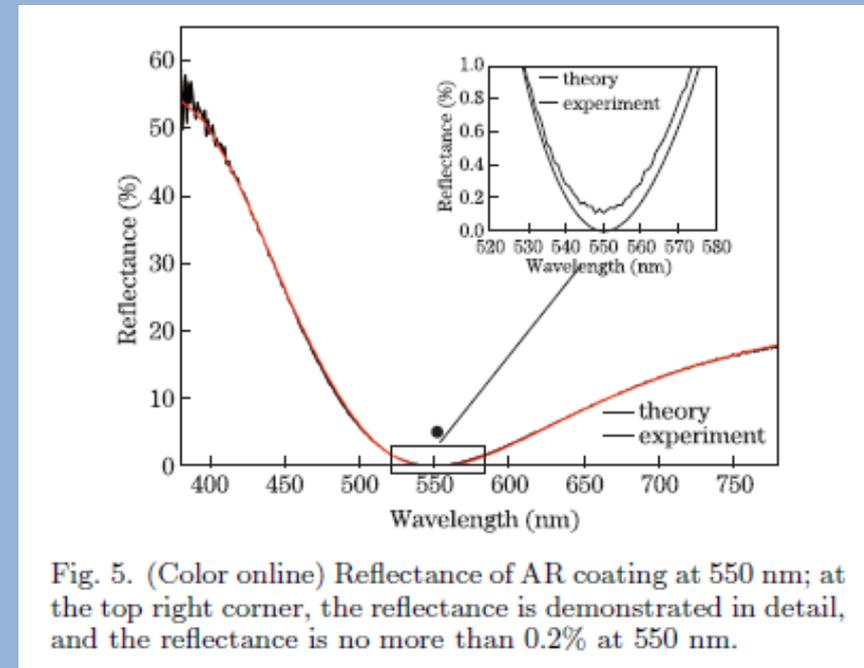


Fig. 5. (Color online) Reflectance of AR coating at 550 nm; at the top right corner, the reflectance is demonstrated in detail, and the reflectance is no more than 0.2% at 550 nm.

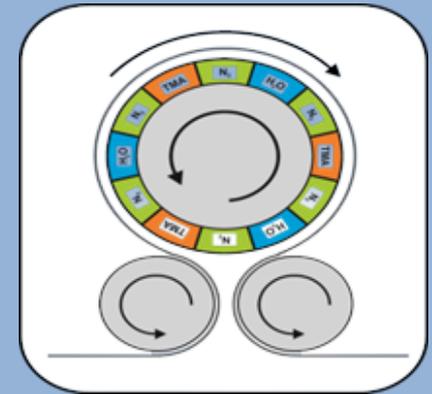
Li et al, Chinese Opt. Lett., COL 11 (Suppl.) S10205(2013)

R2R S-ALD of an optical stack

- Substrate PET
- $\text{TiCl}_4 + \text{H}_2\text{O}$ and $\text{TMA} + \text{H}_2\text{O}$
- Deposition temperature: 100 °C

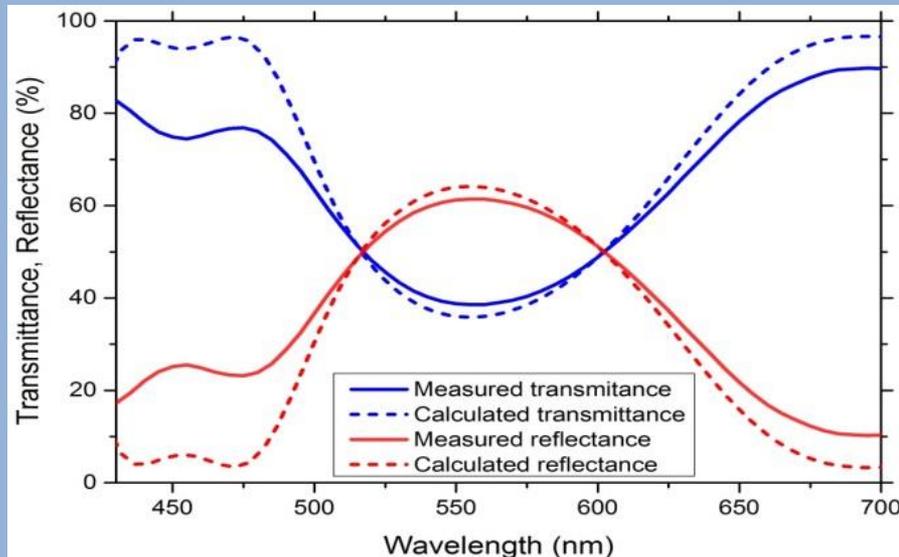


- An optical stack of Al_2O_3 and TiO_2 was calculated to achieve a reflectance maximum at 525 nm on PET foil



R2R S-ALD of an optical stack

- Uniform reflective coating with excellent optical properties
- Transmittance and Reflectance fit excellently with an offset of only $\lambda \sim 28$ nm



Self-cleaning TiO₂

- Both Anatase & Rutile TiO₂ using ALD reported in literature

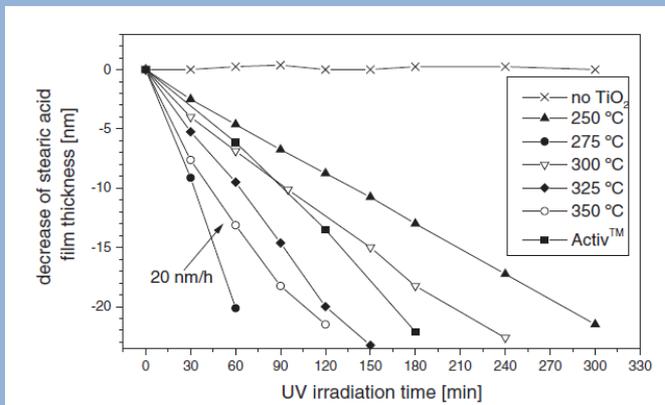


Fig. 5. Time dependence of the stearic acid layer thickness decrease, measured by FTIR, for TiO₂ films deposited at various temperatures. Pilkington Activ self-cleaning glass is included for comparison.

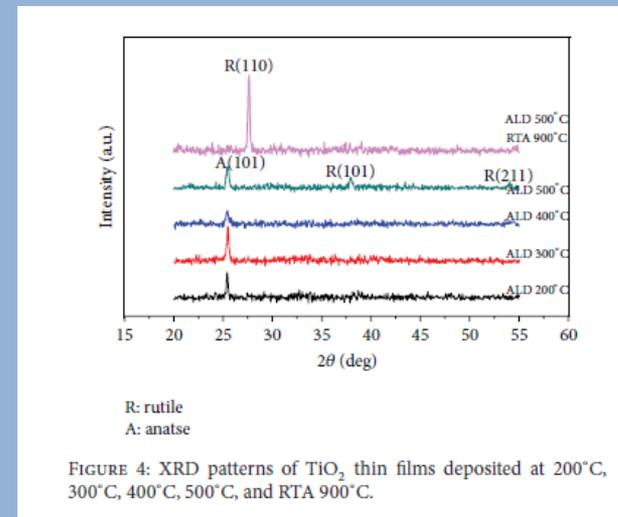


FIGURE 4: XRD patterns of TiO₂ thin films deposited at 200°C, 300°C, 400°C, 500°C, and RTA 900°C.

Anatase: Ti(OMe)₄ + H₂O ALD 250-500°C

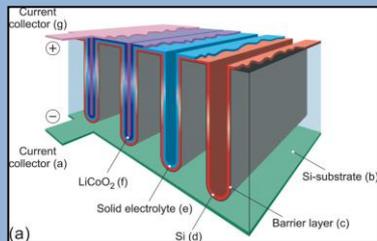
Rutile: TiCl₄ + H₂O ALD 500°C + RTA 900°C

Pore et al, Chem. Vap. Dep. 2004, 10, No.3 p.143

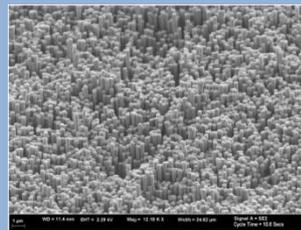
Yu et al, Int. J. Photoenergy, Vol 2013, ID 431614

Introduction: ALD in porous substrates

- ALD is famous for its ability to conformally coat high aspect ratio structures and porous substrates
- New applications are emerging for ALD in porous materials
 - 3D batteries, smart textiles, catalysis, membranes.....



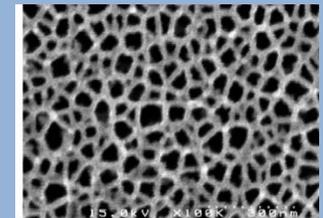
Philips/ Eindhoven University
P. Notten et al, Adv. Mater. 19 (2007) 4564



D. DeMeo et al, Nanotechnology and Nanomaterials » "Nanowires - Implementations and Applications" Chapter 7 (2011)



Tyndall (M.Pemle)
<https://www.youtube.com/watch?v=DG-tNR0mXHO>

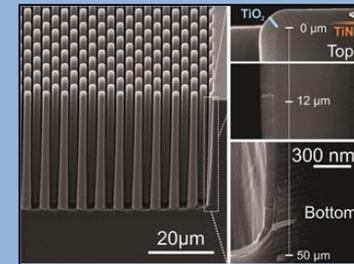
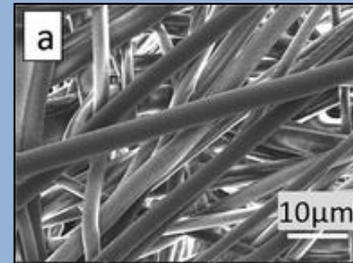
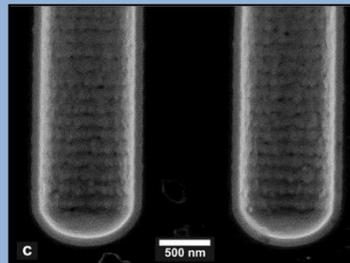
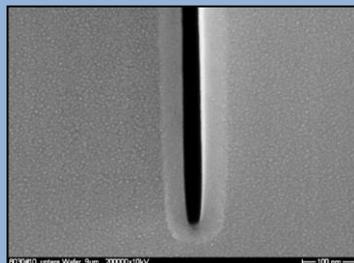
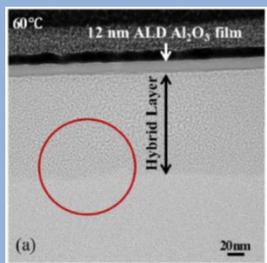


Integrated On-Chip Energy Storage Using Porous-Silicon Electrochemical Capacitors, D.S. Gardner, C.W. Holzwarth, Y. Liu, S.B. Clendenning, W. Jin, B.K. Moon, C.L. Pint, Z. Chen, E. Hannah, R. Chen, C.P. Wang, C. Chen*, E. Mäkilä**, and J.L. Gustafson, Intel Corp., *Florida Int'l Univ., **University of Turku

- Often requires high throughput, large-area, roll-to-roll
- *Can we do this with Spatial ALD?*

Spatial ALD in porous materials

- We have demonstrated *high speed, high step coverage* Spatial ALD at *atmospheric pressure* inside a variety of porous materials
- Many potential applications; Possible to use e.g. Roll-to-Roll Spatial ALD



Polymer modification

Electronics

Catalysis

Textile functionalization

3D batteries

Barriers, membranes and separators

Sensors

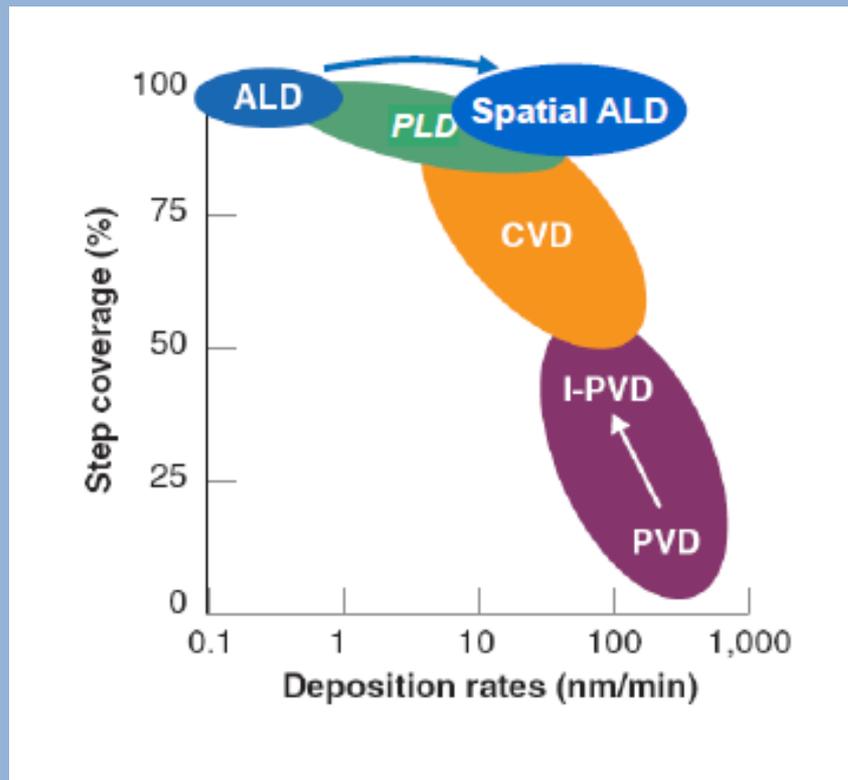
Photovoltaics

Nano-porous

Micro-porous

Conclusions

- Speed enhancement up to 100x brings CoO considerably down → new application opportunities



Conclusions

- **SALD serious competitor for PVD/CVD**
- **Many materials already deposited using S-ALD**
- **Already 4 companies who sell TNO based SALD equipment**
- **Several companies develop products using SALD**
- **Many glass and plastic foil applications possible**

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- Pradeep Panditha
- Peter van der Weijer

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